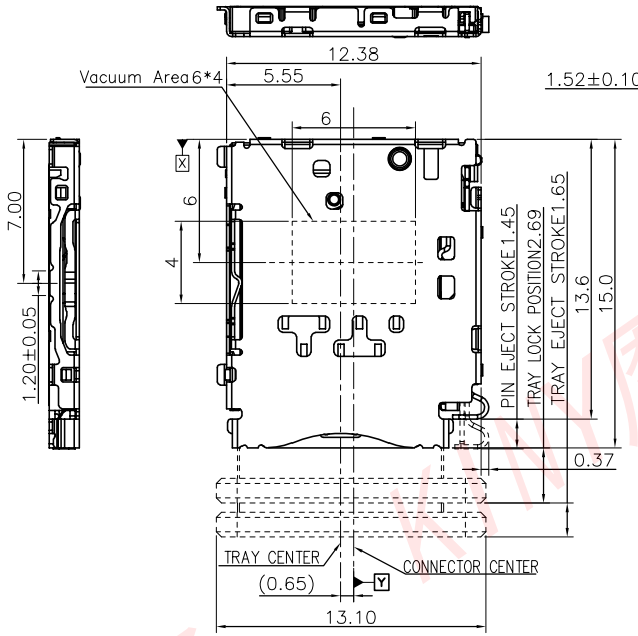
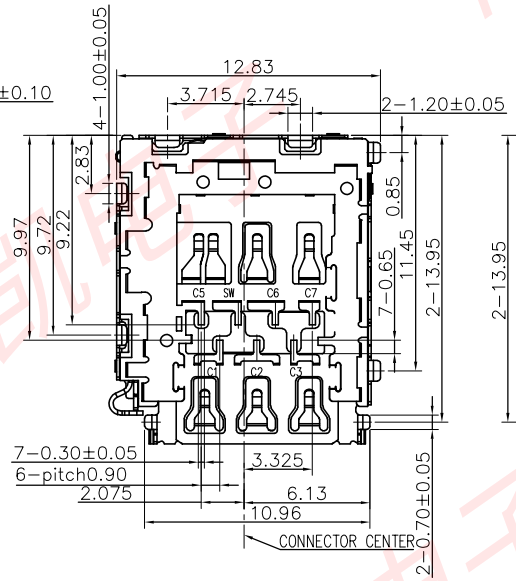
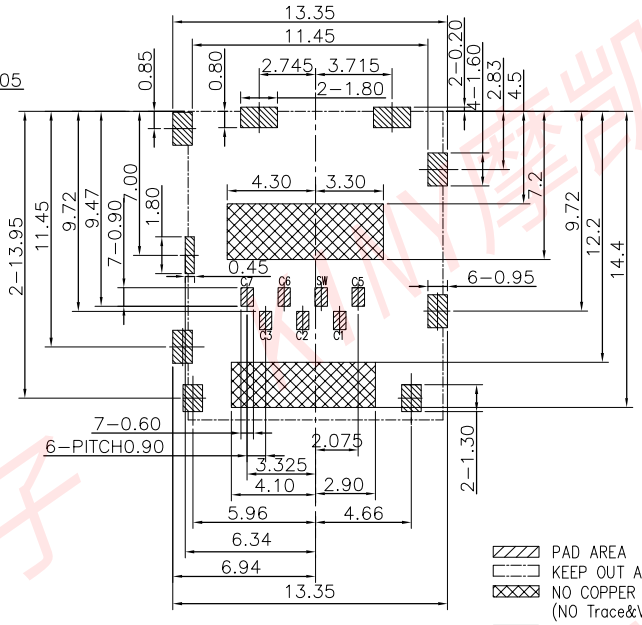
＊ 所有原料材质,生产制程,电镀必须符合HF要求

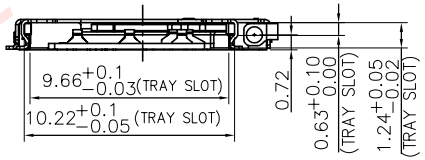






PAD AREA
KEEP OUT AREA
NO COPPER AREA
(NO Trace&Via&GND)
GND PATTERN ONLY

RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

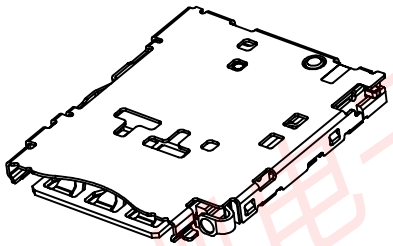


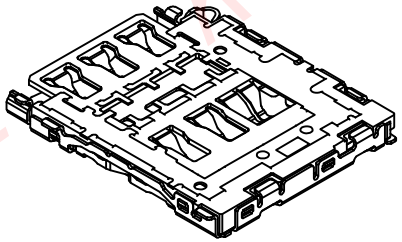
COMPOSITION OF DETECTION
CARD DETECT(SW)
C5 ○—/—○ SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON NON CARD:OFF

NOTE:
1. Material:
   1-1 Housing:High Temperature Thermoplastic,(LCP S475)Color Black UL 94V-0
   1-2 Contact: Phosphor Bronze(C5210R-H,T=0.08±0.01mm)
   1-3 Cover: SUS301-H T=0.15±0.03mm
2. Plating:
   2-1 Contact terminal:
   Contact area: Gold 1u" Min.
   Solder area: Gold 0.8u" Min .
   Underplating: Ni overall 50U" Min.
   2-2 Cover:
   Underplating: Ni overall 30U" Min.
   Solder area: Gold 0.8u" Min .
3. Specification:
   3-1.Current Rating :0.5A max.
   3-2.Contact Resistance: 50 mOhms max
   3-3.Insulation Resistance:1000 MOhms min./500VDC
   3-4.Dielectric Withstanding Voltage:500 V AC/1minute
   3-5.Operating Temperature:-40°C to+85°C
   3-6.Mating Cycles:5000 Insertions
4. Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
5. Part Must Comply Taisol HF WD-3-I-091 Specification.
6. Recommending A Metal More Than 0.15mm Thick.
   Please Confirm Solderadility, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA





REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A	----	NEW RELEASE	PURE	2019.07.15

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : NANO SIM H1.5 CARD	DRAWING: PURE		DATE: 2019.07.15
PRODUCT NO. : NS150-T1131-18	CHECK: Alex		DATE: 2019.07.15
DRAWING NO. : D-NS150-T1131-18	APPROVED: Alex		DATE: 2019.07.15
	SCALE: 1:1	DWG ID: C D	REV.: A / PAGE: 1 OF 1

KINY摩凯电子